

ABSTRACT OF THE DISCLOSURE

The invention provides an image sensor package including a substrate, a frame layer, a photosensitive chip, a plurality of wires, and a transparent layer. The substrate includes plural metal sheets, which are spaced apart and arranged in an alternating manner, each of the metal sheets have a first board and a second board positioned at different heights, the thicken of outside ends of the first board are smaller than the inside ends of the first board, a encapsulate layer encapsulated the plural metal sheets to form a upper surface and a lower surface, so that the outside ends of the first board and the second board are exposed from the encapsulate layer. The frame layer is formed around and under the substrate to form a cavity with the substrate. The photosensitive chip is positioned on upper surface of the substrate and within the cavity. The wires are electrically connecting the outside ends of the first boards to the photosensitive chip. The transparent layer placed on the frame layer to cover the photosensitive chip.